



TSMC Reports Fourth Quarter EPS of NT\$1.61

Hsinchu, Taiwan, R.O.C., January 17, 2013 -- TSMC today announced consolidated revenue of NT\$131.31 billion, net income of NT\$41.57 billion, and diluted earnings per share of NT\$1.61 (US\$0.28 per ADR unit) for the fourth quarter ended December 31, 2012.

Year-over-year, fourth quarter revenue increased 25.4% while net income and diluted EPS increased 31.6% and 31.8%, respectively. Compared to third quarter of 2012, fourth quarter of 2012 results represent a 7.1% decrease in revenue, a 15.7% decrease in net income, and a 15.6% decrease in diluted EPS. All figures were prepared in accordance with R.O.C. GAAP on a consolidated basis.

In US dollars, fourth quarter revenue decreased 4.9% from the previous quarter and increased 30.2% year-over-year.

Gross margin for the quarter was 47.2%, operating margin was 35.2%, and net margin was 31.7%.

Shipments of 28-nanometer process technology reached 22% of total wafer revenues. 40-nanometer accounted for 22% of total wafer revenues, and 65-nanometer was 19%. These advanced technologies accounted for 63% of total wafer revenues.

“In the fourth quarter, demand for our products was higher than we expected three months ago, resulting in above-guidance revenue and profit margins,” said Lora Ho, SVP and Chief Financial Officer of TSMC. “We now expect the supply chain inventory DOI to decline only slightly in the first quarter, and our revenue will also decline only slightly in the first quarter from the previous quarter. Based on our current business outlook and exchange rate assumption of 1 US dollar to 28.90 NT dollars, management expects overall performance for first quarter 2013 to be as follows”:

- Revenue is expected to be between NT\$127 billion and NT\$129 billion;
- Gross profit margin is expected to be between 43.5% and 45.5%;
- Operating profit margin is expected to be between 31.5% and 33.5%.

TSMC further expects the capital expenditures for 2013 to be about US\$9 billion.

Conference Call & Webcast Notice:

TSMC's quarterly conference call will be held in conjunction with the Earnings Conference at 1 a.m. Eastern Time (2 p.m. Taiwan Time) on Thursday January 17, 2013. The event will be webcast live, and archived for replay within 3 hours on TSMC's website at <http://www.tsmc.com>. A transcript will be available for download within 24 hours after the Earnings Conference is finished. Investors wishing to access the live webcast should visit TSMC's web site at <http://www.tsmc.com> at least 15 minutes prior to the broadcast. Instructions will be provided on the web site to facilitate the download and installation of necessary audio applications. Investors without Internet access may listen to the conference call, in listen-only mode, by dialing **1-718-354-1231** in the U.S., **852-2475-0994** in Hong Kong, and **44-203-059-8139** in the U.K. (Password: TSMC).

Profile

TSMC is the world's largest dedicated semiconductor foundry, providing the industry's leading process technology and the foundry's largest portfolio of process-proven libraries, IPs, design tools and reference flows. The Company's managed capacity in 2012 was about 15.1 million (8-inch equivalent) wafers, including capacity from three advanced 12-inch GIGAFABs™, four eight-inch fabs, one six-inch fab, as well as TSMC's wholly owned subsidiaries, WaferTech and TSMC China, and its joint venture fab, SSMC. TSMC is the first foundry to provide 28nm production capabilities. Its corporate headquarters are in Hsinchu, Taiwan. For more information about TSMC please visit <http://www.tsmc.com>.

(Management Report and Tables Follow)

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Safe Harbor Notice:

The statements included in this press release that are not historical in nature are "forward-looking statements" within the meaning of the "safe harbor" provisions of the Private Securities Litigation Reform Act of 1995. TSMC cautions readers that forward-looking statements are subject to significant risks and uncertainties and are based on TSMC's current expectations. Actual results may differ materially from those contained in such forward-looking statements for a variety of reasons including, among others, risks associated with cyclical and market conditions in the semiconductor industry; demand and supply for TSMC's foundry manufacturing capacity in particular and for foundry manufacturing capacity in general; intense competition; the failure of one or more significant customers to continue to place the same level of orders with us; TSMC's ability to remain a technological leader in the semiconductor industry; TSMC's ability to manage its capacity; TSMC's ability to obtain, preserve and defend its intellectual property rights; natural disasters and other unexpected events which may disrupt production; and exchange rate fluctuations. Additional information as to these and other risk factors that may cause TSMC's actual results to differ materially from TSMC's forward-looking statements may be found in TSMC's Annual Report on Form 20-F, filed with the United States Securities and Exchange Commission (the "SEC") on April 13, 2012, and such other documents as TSMC may file with, or submit to, the SEC from time to time. Except as required by law, we undertake no obligation to update any forward-looking statement, whether as a result of new information, future events, or otherwise.